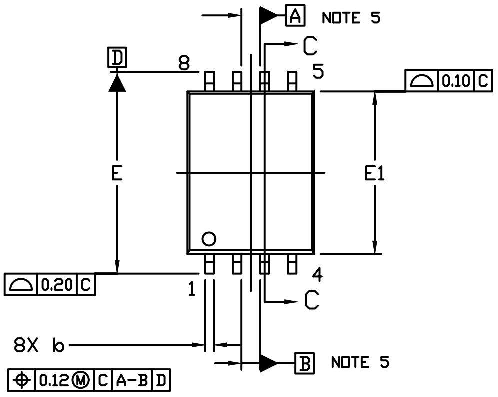
SOIC8 WB

CASE 751EW
ISSUE A

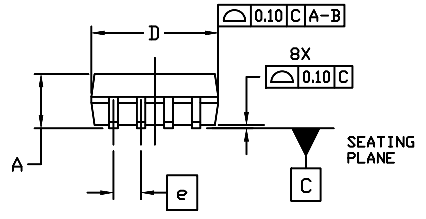
DATE 31 MAY 2019



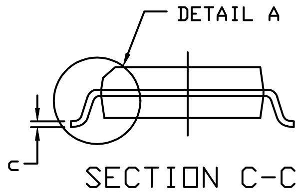
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM H.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. NO JEDEC STANDARD AT TIME OF SETUP.

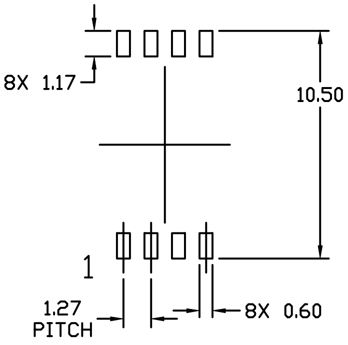


SIDE VIEW

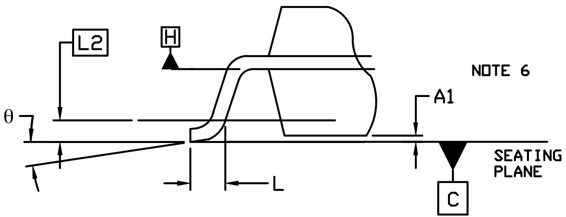


SECTION C−C

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.35	2.50	2.65
A1	0.10	0.20	0.30
b	0.31	0.41	0.51
c	0.20	0.27	0.33
D	5.65	5.85	6.05
E	10.11	10.31	10.51
E1	7.40	7.50	7.60
e	1.27 BSC		
L	0.40	0.58	0.75
L2	0.25 BSC		
θ	0°	---	8°

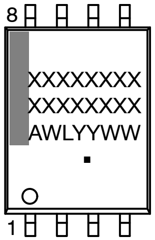


RECOMMENDED MOUNTING FOOTPRINT



DETAIL A

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present. Some products may not follow the Generic Marking.

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